

# MBRAF1100T3G

## Schottky Power Rectifier

### Surface Mount Power Package

Schottky Power Rectifiers employ the use of the Schottky Barrier principle in a large area metal-to-silicon power diode. State-of-the-art geometry features epitaxial construction with oxide passivation and metal overlay contact. Ideally suited for low voltage, high frequency rectification, or as free wheeling and polarity protection diodes, in surface mount applications where compact size and weight are critical to the system. These state-of-the-art devices have the following features:

#### Features

- Rectangular Package for Automated Handling
- Highly Stable Oxide Passivated Junction
- High Blocking Voltage – 100 V
- 150°C Operating Junction Temperature
- Guardring for Stress Protection
- This is a Pb-Free Device

#### Mechanical Characteristics

- Case: Epoxy, Molded
- Weight: 95 mg (approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Shipped in 12 mm Tape and Reel, 5000 Units per Reel
- Cathode Polarity Band

#### MAXIMUM RATINGS

| Rating   | Symbol                          | Value       | Unit |
|--|---------------------------------|-------------|------|
| Peak Repetitive Reverse Voltage<br>Working Peak Reverse Voltage<br>DC Blocking Voltage                         | $V_{RRM}$<br>$V_{RWM}$<br>$V_R$ | 100         | V    |
| Average Rectified Forward Current<br>$T_L = 130^\circ\text{C}$   | $I_{F(AV)}$                     | 1.0         | A    |
| Non-Repetitive Peak Surge Current<br>(Surge Applied at Rated Load Conditions<br>Halfwave, Single Phase, 60 Hz) | $I_{FSM}$                       | 50          | A    |
| Operating Junction Temperature (Note 1)  | $T_J$                           | -65 to +150 | °C   |
| Voltage Rate of Change   | $dv/dt$                         | 10          | V/ns |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

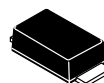
1. The heat generated must be less than the thermal conductivity from Junction-to-Ambient:  $dP_D/dT_J < 1/R_{\theta JA}$ .



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### SCHOTTKY BARRIER RECTIFIER 1.0 AMPERE 100 VOLTS



SMA-FL  
CASE 403AA  
STYLE 6

#### MARKING DIAGRAM



RAD = Device Code  
A = Assembly Location  
Y = Year  
WW = Work Week  
■ = Pb-Free Package

#### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

# MBRAF1100T3G

## THERMAL CHARACTERISTICS

| Characteristic                                   | Symbol          | Value | Unit                 |
|--|-----------------|-------|----------------------|
| Thermal Resistance, Junction-to-Lead (Note 2)    | $R_{\theta JL}$ | 25    | $^{\circ}\text{C/W}$ |
| Thermal Resistance, Junction-to-Ambient (Note 2) | $R_{\theta JA}$ | 90    |                      |

2. 1 inch square pad size ( $1 \times 0.5$  inch) for each lead on FR4 board.

## ELECTRICAL CHARACTERISTICS

| Rating  | Symbol | Value      | Unit |
|---|--------|------------|------|
| Maximum Instantaneous Forward Voltage (Note 4) ( $I_F = 1.0$ A, $T_J = 25^{\circ}\text{C}$ )  | $V_F$  | 0.75       | V    |
| Maximum Instantaneous Reverse Current (Note 4)<br>(Rated dc Voltage, $T_J = 25^{\circ}\text{C}$ )<br>(Rated dc Voltage, $T_J = 100^{\circ}\text{C}$ ) | $I_R$  | 0.5<br>5.0 | mA   |

3. 1 inch square pad size ( $1 \times 0.5$  inch) for each lead on FR4 board.

4. Pulse Test: Pulse Width = 300  $\mu\text{s}$ , Duty Cycle  $\leq 2.0\%$ .

## ORDERING INFORMATION

| Device       | Marking | Package             | Shipping <sup>†</sup> |
|--------------|---------|---------------------|-----------------------|
| MBRAF1100T3G | RAD     | SMA-FL<br>(Pb-Free) | 5000 / Tape & Reel    |

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

## TYPICAL ELECTRICAL CHARACTERISTICS

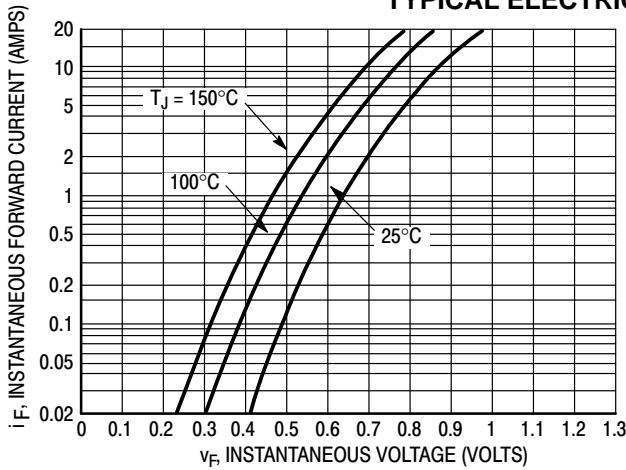


Figure 1. Typical Forward Voltage

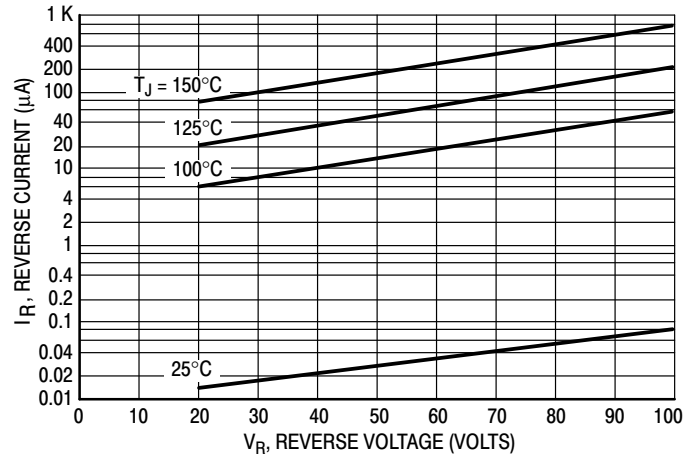


Figure 2. Typical Reverse Current\*

\*The curves shown are typical for the highest voltage device in the voltage grouping. Typical reverse current for lower voltage selections can be estimated from these curves if  $V_R$  is sufficient below rated  $V_R$ .

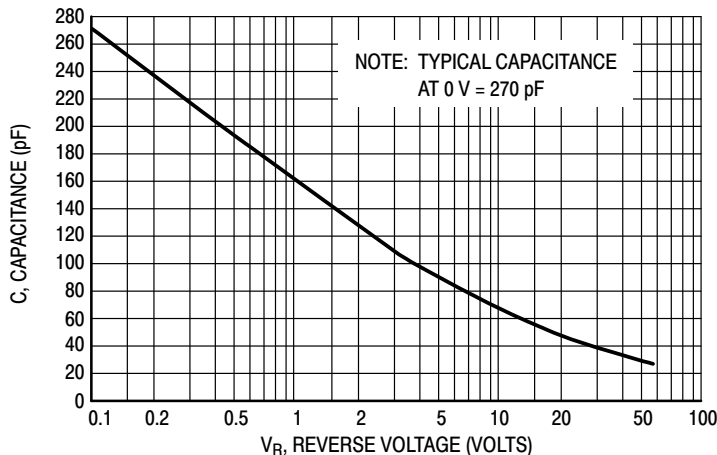


Figure 3. Typical Capacitance

# MBRAF1100T3G

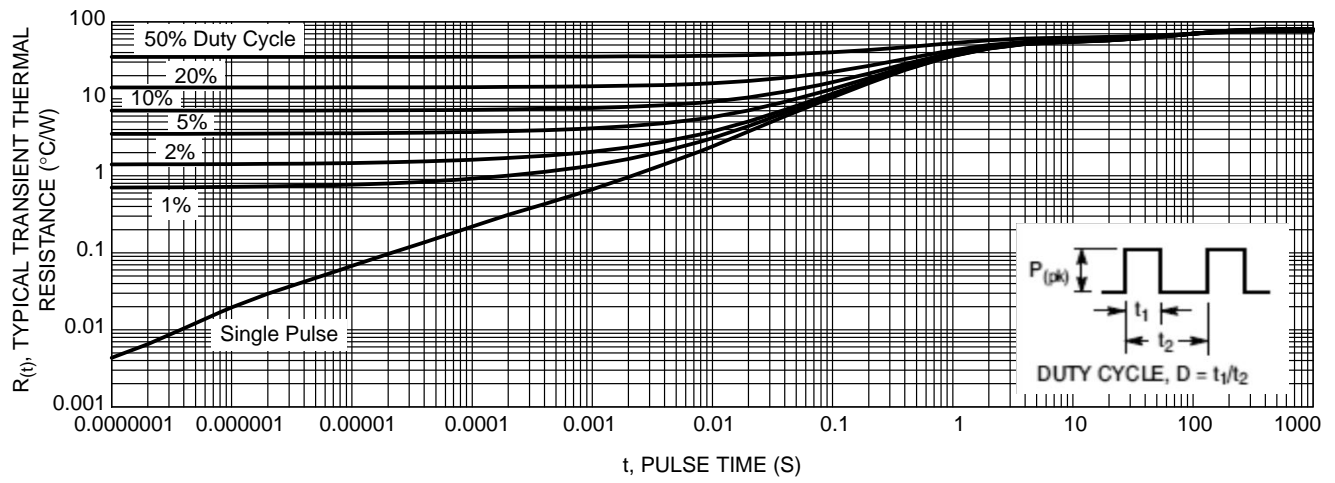
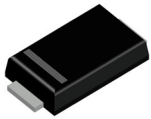
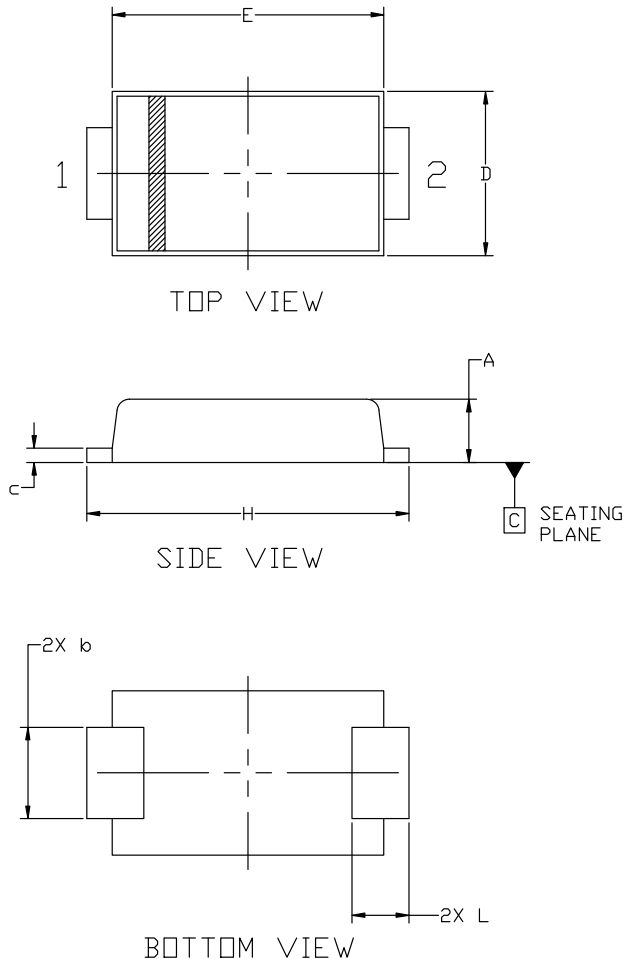


Figure 4. Typical Transient Thermal Response, Junction-to-Ambient



**SMA 2.60x4.30x1.00**  
**CASE 403AA**  
**ISSUE A**

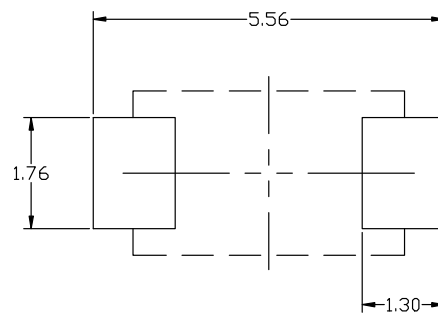
DATE 18 JAN 2024



**NOTES:**

1. DIMENSIONING AND TOLERANCING AS PER ASME Y14.5M, 2018.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. FL

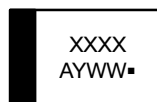
| MILLIMETERS |      |       |      |
|-------------|------|-------|------|
| DIM         | MIN  | NOM   | MAX  |
| A           | 0.90 | 1.00  | 1.10 |
| b           | 1.25 | 1.45  | 1.65 |
| c           | 0.15 | 0.225 | 0.30 |
| D           | 2.40 | 2.60  | 2.80 |
| E           | 4.00 | 4.30  | 4.60 |
| H           | 4.80 | 5.10  | 5.40 |
| L           | 0.70 | 0.90  | 1.10 |



**RECOMMENDED MOUNTING FOOTPRINT**

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference manual, SOLDERRM/D.

**GENERIC MARKING DIAGRAM\***



XXXX = Specific Device Code  
A = Assembly Location  
Y = Year  
WW = Work Week  
▪ = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

|                         |                           |  |
|-------------------------|---------------------------|--|
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